Initial Product/Process Change Notification

Document #: IPCN25133X
Issue Date: 14 Dec 2022

Title of Change:	WDFN6L Clip Transfer from Cebu to Seremban.
Proposed First Ship date:	01 Aug 2023 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office or saziela.senin@onsemi.com
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Marking of Parts/ Traceability of Change:	Material will be traceable with onsemi lot trace code and tracking
Change Category:	Test Change, Assembly Change
Change Sub-Category(s):	Manufacturing Site Transfer

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Seremban, Malaysia	None

Description and Purpose:

This Initial Product Change Notification is to announce that onsemi intends to transfer WDFN6L Clip devices from onsemi Cebu, Philippines to onsemi Seremban, Malaysia.

	From	To
Lead Frame	ETCHED LEADFRAME, PQFN 2.0X2.0 MM, 6LDS FULL DRAIN	WDFN 2.05X2.05 6L 0.65P WIDE LEADFRAME
Clip	ETCHED CLIPFRAME, PQFN, 2.0 X 2.0 MM POWERCLIP SINGLE.	Etch Clip wDFN6L 2.05x2.05 0.65P
Solder	DA SLDR PASTE IND 92.5Pb5Sn2.5Ag NC-SMQ75	DA IN SDR SN5AG2.5PB92.5
Solder	DA SLDR PASTE IND 92.5Pb5Sn2.5Ag NC-SMQ75 (Clip Attach material)	DA IN SDR SN5AG2.5PB92.5 (Clip Attach material)
Mold Compound	MC GREEN HI CEL9240HF10LS 14MMX6.6G	SUMITOMO EME-G770HM TYPE D
Assembly Site	onsemi Cebu, Philippines	onsemi Seremban, Malaysia
Test Site	onsemi Cebu, Philippines	onsemi Seremban, Malaysia

There is no product marking change as a result of this change.

Qualification Plan:

QV DEVICE NAME: NTLJS17D0P03P8ZTAG
RMS: 85779
PACKAGE: WDFN 2X2

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs
HTGB	JESD22-A108	Ta=150°C, 100% max rated Vgss	1008 hrs
HTSL	JESD22-A103	Ta= 150C	2016 hrs
PC	J-STD-020 JESD-A113	MSL 1 @ 260 °C	
IOL	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	30000 cyc
TC	JESD22-A104	Ta= -55°C to +150°C, mount on board	1000 cyc
HAST	JESD22-A110	130°C, 85% RH, 18.8psig, bias	192 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs
RSH	JESD22- B106	Ta = 265°C, 10 sec Required for through hole devices only	
SD	JSTD002	Ta = 245°C, 5 sec	

Estimated date for qualification completion: **7 May 2023**

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

Part Number	Qualification Vehicle
NTLJS17D0P03P8ZTAG	NTLJS17D0P03P8ZTAG
NTLJS7D2P02P8ZTAG	NTLJS17D0P03P8ZTAG
NTLJS3D0N02P8ZTAG	NTLJS17D0P03P8ZTAG